1-104074-0 ACTIVE

AMPMODU | AMPMODU System 50

TE Internal #: 1-104074-0

PCB Mount Header, Right Angle, Board-to-Board, 8 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, Through Hole -

Solder, AMPMODU System 50

View on TE.com >



Connectors > PCB Connectors > PCB Headers & Receptacles











PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Right Angle
Connector System: Board-to-Board

Number of Positions: 8

Number of Rows: 1

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Right Angle
Number of Positions	8
Number of Rows	1
Board-to-Board Configuration	Perpendicular

Electrical Characteristics

Dielectric Withstanding Voltage (Max)	500 VAC
Insulation Resistance	5000 MΩ



Operating Voltage	30 VAC
Body Features	
PCB Retention Feature Plating Material	Tin-Lead over Nickel
Connector Profile	Standard
Primary Product Color	Black
Contact Features	
Mating Square Post Dimension	.38 mm[.015 in]
PCB Contact Termination Area Plating Material Thickness	3.81 – 6.35 μm[150 – 250 μin]
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Rectangular
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.76 μm[30 μin]
Contact Type	Pin
Contact Current Rating (Max)	3.6 A
Termination Features	
Round Termination Post & Tail Diameter	.38 mm[.015 in]
Termination Post & Tail Length	2.54 mm[.1 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Retention	With
PCB Mount Retention Type	Hold-Down Post
Mating Retention Type	Latching
Mating Alignment	With
Mating Alignment Type	Polarization
PCB Mount Retention	With
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	1.27 mm[.05 in]



Housing Material	LCP
Dimensions	
PCB Thickness (Recommended)	1.57 mm[.062 in]
Usage Conditions	
Housing Temperature Rating	High
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
UL Rating	Recognized
	Treeogrifized
Agency/Standard	CSA, UL
Agency/Standard	CSA, UL
Agency/Standard Approved Standards	CSA, UL CSA LR7189, UL E28476
Agency/Standard Approved Standards UL Flammability Rating	CSA, UL CSA LR7189, UL E28476
Agency/Standard Approved Standards UL Flammability Rating Packaging Features	CSA, UL CSA LR7189, UL E28476 UL 94V-0

Product Compliance

Position Locations Omitted

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Not Compliant
EU ELV Directive 2000/53/EC	Compliant with Exemptions
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) SVHC > Threshold: Pb (13% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC

0

PCB Mount Header, Right Angle, Board-to-Board, 8 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU System 50



Free

Solder Process Capability

Wave solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts





Also in the Series | AMPMODU System 50



Customers Also Bought





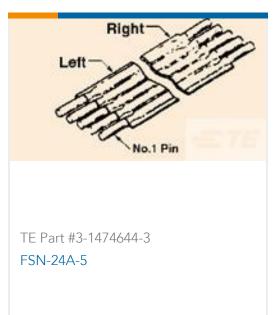


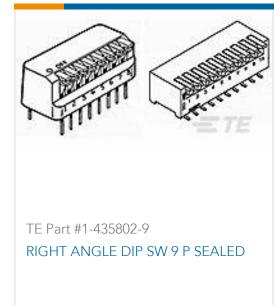














Documents

Product Drawings

08 SYSTEM 50 HDR SRRA SHRD

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1-104074-0_W.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1-104074-0_W.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1-104074-0_W.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English

Product Environmental Compliance

TE Material Declaration

English